VIIYONG

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GUANGDONG VIIYONG ELECTRONIC TECHNOLOGYCO., LTD.

Multi-layer Ceramic Chip Capacitor
Product Specification

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Mark：The product specification is only for reference of design and type selection, not used as the basis for delivery.

1. Scope:

The specifications are applicable to the multi-layer ceramic chip capacitor (MLCC) as follows:

1.1 Application characteristics: general purpose;

1.2 Structural design classification: general;

Chip Size: 0402、0603、0805、1206;

Capacitance: 1pF~1μF;

Voltage range: 6.3V~50V;

1.3 Type of Dielectrics: C0G/C0H(NP0)、X7R、X5R、Y5V;

2. Part Number System:

V 104 K 0402 X5R 160 N B *

General-purpose MLCC	**Rated Capacitance** For example: 0R5=0.5pF 101=100pF		**Size Code** (EIA size) 0402; 0603 0805; 1206	**Type of Dielectrics** C0G、X5R X7R、Y5V	**Rated Voltage** 6R3=6.3V; 100=10V 160=16V ; 250=25V 500=50V		**Control code**

Capacitance Tolerance

A: ±0.05pF	B: ±0.1pF	C: ±0.25 pF	D: ±0.5pF
F: ±1%	G: ±2%	J: ±5%	K: ±10%
L: ±15%	M: ±20%	N: ±30%	X: ±40%
Z: +80/-20%			
Y: +150/-20%			

Termination Type

N: Cu /Ni/Sn structure;

Thickness Code

Details are shown in Table1.

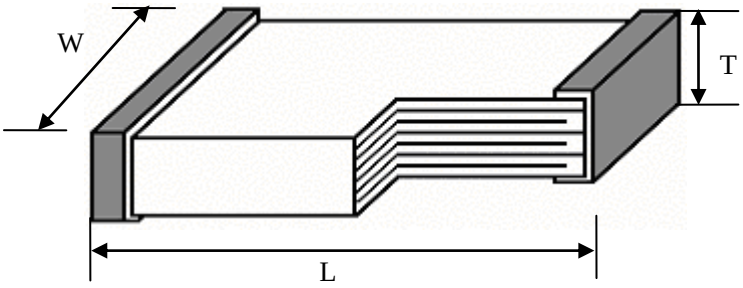


Fig.1 Configuration and Dimension of MLCC

Table 1 Dimension of MLCC (Unite: mm)

Size	Length (L)	Width (W)	Width of Termination (L1、L2)	Thickness (T)	Thickness code
0402	1.00±0.05	0.50±0.05	0.10～0.35	0.50±0.05	B
	$1.00^{+0.15}_{-0.05}$	$0.50^{+0.13}_{-0.05}$	0.10～0.35	$0.50^{+0.13}_{-0.05}$	N
0603	1.60±0.10	0.80±0.10	0.15～0.60	0.80±0.10	D
0805	2.00±0.20	1.25±0.20	0.20～0.75	$0.85^{+0.15}_{-0.35}$	Y
	$2.00^{+0.20}_{-0.30}$	$1.25^{+0.20}_{-0.30}$	0.20～0.75	$1.25^{+0.20}_{-0.30}$	H
1206	3.20±0.20	1.60±0.20	0.25～0.75	$0.85^{+0.15}_{-0.35}$	Y
	3.20±0.20	1.60±0.20	0.25～0.75	1.15±0.20	O
	3.20±0.20	1.60±0.20	0.25～0.75	1.60±0.20	L

Table 2 Type of dielectrics

Type of Dielectrics	Operating Temperature Range	Temperature Coefficient or Characteristic
NP0	-55℃～+125℃	C0G：0±30ppm/℃
		C0H：0±60ppm/℃
X7R	-55℃～+125℃	±15%
X5R	-55℃～+85℃	±15%
Y5V	-30℃～+85℃	+22/-82%

Table 3 Rated Voltage and Rated Capacitance

Size	Rate voltage /U_R	Capacitance				Thickness code
		C0G	X7R	X5R	Y5V	
0402	50V	1pF～1.0nF	100pF～56nF	100pF～22nF	100pF～22nF	B
		360pF～1.0nF	22nF～100nF	27nF～47nF	33nF～47nF	N
	25V	1pF～1.0nF	22nF～100nF	10nF～100nF	10nF～68nF	B
		470pF～1.0nF	100nF	82nF～100nF	100nF	N
	16V	—	56nF～100nF	47nF～100nF	47nF～150nF	B
		—	—	120nF～220nF	150nF～220nF	N
	10V	—	—	100nF	100nF	B
		—	—	120nF～220nF	150nF～220nF	N
	6.3V	—	—	220nF	220nF	N
0603	50V	1pF～2.2nF	220pF～100nF	220pF～100nF	220pF～220nF	D
	25V	2.7nF～3.9nF	100nF～390nF	100nF～220nF	100nF～220nF	D
	16V	—	100nF～390nF	220nF～470nF	220nF～470nF	D
0805	50V	10pF～4.7nF	220pF～100nF	220pF～100nF	220pF～100nF	Y
		1.0nF～5.6nF	100nF～820nF	100nF～820nF	100nF～680nF	H
	25V	1.0nF～10nF	—	—	—	Y
		—	220nF～820nF	220nF～820nF	220nF～680nF	H
	16V	—	1.0μF	1.0μF	1.0μF	H
1206	50V	—	100nF	—	100nF	Y
		—	100nF～1.0μF	—	100nF～1.0μF	L
	16V	—	1.0μF	—	1.0μF	O

Note: 1) E12 series for X7R and X5R groups, E6 series for Y5V group, E24 series for C0G group, integer nominal values such as 1.0, 2.0, 3.0pF, etc. are allowed for the specifications below 10pF.

2) For products of the same size, material and capacity, the rated voltage can be covered from high to low.

Type of Packing：

Reel Packaging (standard carrier tape disc packaging), every disc smallest package are shown in Table 4.

Table 4 Packing type

Chip Size	0402		0603	0805		1206	
Thickness code	B/N	B/N	D	H	Y	L/O	Y
Disc size	7”	13”	7”	7”	7”	7”	7”
Carrier Tape type	Paper	Paper	Paper	Plastic	Paper	Plastic	Paper
QTY (Kpcs)	10	50	4	2	4	2	4

First packaging: Each multi-disc material is packed into a box.

The second packaging: the first packaged packaging box is loaded into the paper packaging box, and the remaining space in the box is filled with light auxiliary materials. The above packaging forms can also be packaged according to user needs.

3. Technical specifications and test methods：

3.1 Visual Inspection：

3.1.1 Requirement: no obvious defects on ceramic body and termination.

3.1.2 Test Method: Microscope 10×.

3.2 Size:

3.2.1 Requirement: Configuration and dimension of MLCC are shown in Figure 1 and Table 1.

3.2.2 Test Method: Measuring by gages which precision is not less than 0.01 mm .

3.3 Operating Environment:

C0G/C0H(NP0), X7R	Temperature： -55℃～+125℃;Relative humidity： ≤95%（25℃）	Atmosphere：86kPa ～106KPa
X5R	Temperature： -55℃～+85℃； Relative humidity： ≤95%（25℃）	Atmosphere： 86kPa ～106KPa
Y5V	Temperature： -30℃～+85℃； Relative humidity： ≤95%（25℃）	Atmosphere： 86kPa ～106KPa

3.4 Electrical Parameters and Test Methods:

Table 5 Specifications and Test Methods of MLCC Electrical Parameter

<table>
<tr><th>No.</th><th>Item</th><th>Specification</th><th>Test Method</th></tr>
<tr><td>1</td><td>Capacitance（C）</td><td colspan="2">Within the specified tolerance</td><td rowspan="3">Temperature： 18～28℃；
Humidity： ≤RH 80%；
Test frequency：
C0G/C0H(NP0)：
C≤1000pF, f=1MHz±10%；
C>1000pF, f=1KHz±10%
X7R、 X5R、 Y5V：
C≤100pF, f=1MHz±10%；
C>100pF, f=1KHz±10%
Test Voltage：
C≤100pF 1.0±0.2Vrms；
100pF＜C≤1μF： 1.0±0.2Vrms</td></tr>
<tr><td rowspan="2">2</td><td rowspan="2">Tangent of Loss Angle/ (tgδ)</td><td colspan="2">C0G/C0H(NP0)： C≥30pF，tgδ≤10×10^{-4}；
C<30pF， tgδ≤$1.0\times(90/C+7)\times10^{-4}$</td></tr>
<tr><td>X7R：
U_R=50V tgδ≤350×10^{-4}
U_R =25V tgδ≤480×10^{-4}
U_R ≤16V tgδ≤500×10^{-4}</td><td>X5R：
U_R =50V/25V tgδ≤750×10^{-4}
U_R =16V tgδ≤800×10^{-4}
U_R =10V tgδ≤900×10^{-4}
U_R=6.3V
tgδ≤1000×10^{-4}</td></tr>
<tr><td colspan="2">Y5V： U_R ≥25V tgδ≤950×10^{-4}
U_R =16V tgδ≤1300×10^{-4}
U_R≤10V tgδ≤1600×10^{-4}</td></tr>
<tr><td rowspan="2">3</td><td rowspan="2">Insulation Resistances/ (Ri)</td><td colspan="2">C0G/C0H(NP0)： C≤10nF，Ri≥10000MΩ
C>10nF，Ri×C≥500s</td><td rowspan="2">Temperature： 18～28℃；
Humidity： ≤RH 80%；
Apply rated voltage within 60 ±5S</td></tr>
<tr><td>X7R、X5R：
C≤25nF，Ri≥4000MΩ
C>25nF，Ri×C≥100s</td><td>Y5V：
C≤25nF, Ri≥4000MΩ
C>25nF, Ri×C≥100s</td></tr>
<tr><td>4</td><td>Withstanding voltage（WV）</td><td colspan="2">No breakdown or flashover during test</td><td>C0G/C0H(NP0)： $3\times U_R$
X7R、X5R、Y5V： $2.5\times U_R$
t=1minute
Charge/discharge current not exceeds 50mA.</td></tr>
</table>

Note: Capacitance test instructions of Class 2 ceramic capacitors

When the capacitor initial capacitance is lower than its tolerance value, the test sample need to be heated for 60 ± 5 minutes at 150 ℃ ±10 ℃. Recover it, let sit at room temperature for 24±2 hrs, and then test the capacitance.

3.5 Environment Test Specifications and Methods：

Without specific note, the “test method” in Table 6 is based on GB/T 21041/21042 IDT IEC60384-21/22 .

Table 6 Environment Test Specifications and Methods

<table>
<tr><th>No.</th><th>Item</th><th>Specification</th><th>Test Method</th></tr>
<tr><td rowspan="3">1</td><td rowspan="3">Temperature Coefficient of Capacitance (α_c) or Temperature Characteristics</td><td>NP0(C0G/C0H)：
$\alpha_c \leq \pm30$ppm/℃ (125℃);
$-72\leq\alpha_c\leq+30$ppm/℃ (-55℃);</td><td rowspan="3">Preliminary Drying for 16~24hrs C0G/C0H(NP0),Special preconditioning for 1hr at 150℃ followed by 24hrs（X7R、X5R、Y5V）,The ranges of capacitance change compared with the temperature ranges (θ1, 25℃, θ2) shall be within the specified ranges.
X5R： θ1=-55℃， θ2=85℃
X7R： θ1=-55℃， θ2=125℃
Y5V： θ1=-30℃， θ2=85℃
Test voltage：
0402 X7R 27nF≤C≤100nF：0.5±0.1Vrms
others： 1.0±0.2Vrms</td></tr>
<tr><td>X7R,X5R： ΔC/C ≤ ±15%</td></tr>
<tr><td>Y5V： -82%≤ΔC/C≤+22%</td></tr>
</table>

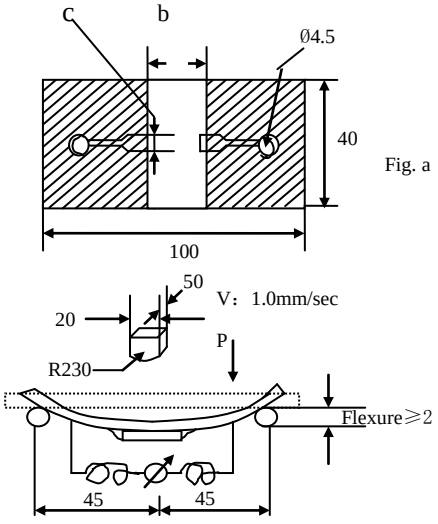
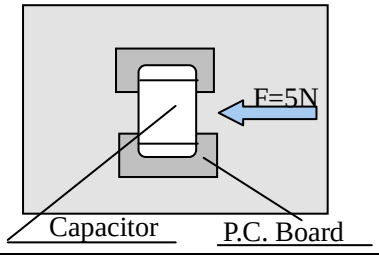
<table>
<tr><td rowspan="3">2</td><td rowspan="3">Resistance to Soldering Heat</td><td>Visual: No visible damage and terminations uncovered shall be less than 25%.</td><td rowspan="3">Special preconditioning for 1hr at 150℃ followed by 24±1hrs;Preheat the capacitor at 110 to 150℃ for 30-60s. Immerse the capacitor in an eutectic solder solution at 260±5℃ for 10±1 seconds. The depth of immersion is 10mm.
Recover it, let sit at room temperature for 6~24hrs[C0G/C0H(NP0)] or 24 ± 2hrs（X7R、X5R、Y5V）, then observe appearance and measure electrical characteristics.</td></tr>
<tr><td>Capacitance Change:
NP0(C0G/C0H): ΔC/C ≤ ±2.5% or ±0.25pF, whichever is larger;
X7R, X5R: ΔC/C≤±7.5%;
Y5V: ΔC/C ≤ ±20%</td></tr>
<tr><td>tgδ and Ri: meet the initial specification in Table 5.</td></tr>
<tr><td>3</td><td>Solderability</td><td>75% min. coverage of both terminal electrodes is soldered evenly and continuously.</td><td>Immerse the test capacitor into a methanol solution containing rosin for 3 to 5 seconds, preheat it at 80 to 180℃ for 30s to 60s and immerse it into molten solder of 235±5℃ for 2±0.2 seconds. The depth of immersion is 10mm.</td></tr>
<tr><td>4</td><td>Bond Strength of Termination</td><td>Visual: No visible damage.
Capacitance Change:
NP0(C0G/C0H): ΔC/C ≤ ±5% or ±0.5pF, whichever is larger;
X7R, X5R: ΔC/C≤±12.5%;
Y5V: ΔC/C ≤ ±30%</td><td>Solder the capacitor to the test jig (glass epoxy boards) shown in Fig. a. Apply a force in the direction shown in Fig. b. Bending 2mm at a speed of 1mm/sec and hold for 5±1secs, then measure the capacitance.
 

Fig. a
Capacitance meter Fig. b (Unit：mm)</td></tr>
<tr><td>5</td><td>Adhesion</td><td>Visual: No visible damage.</td><td>When Soldering the capacitor on a P. C. board, apply a pushing force of 5N for 10±1secs.
 
</td></tr>
</table>

6	Vibration	**Visual:** No visible damage. **Capacitance Change:** **NP0(C0G/C0H)**: ΔC/C ≤ ±2.5% or ±0.25pF, whichever is larger; **X7R, X5R**: ΔC/C≤±7.5%; **Y5V**: ΔC/C ≤ ±20% **tgδ and Ri:** meet the initial specification in Table 5.	Sample shall be mounted on a suitable substrate. **Amplitude:** 1.5mm **Frequencies:** 10 Hz~55 Hz and Harmonic vibration of uniform changes, 1 minutes sweep cycle. Repeat this for 2hrs each in 3 perpendicular directions X, Y, Z, total 6hrs. (Related STD: IEC 68-2-6 test Fc)
7	Rapid change of temperature	**Visual:** No visible damage. **Capacitance Change:** **NP0(C0G/C0H)**: ΔC/C ≤ ±2.5% or ±0.25pF, whichever is larger; **X7R, X5R**: ΔC/C≤±15%; **Y5V**: ΔC/C ≤ ±20% **tgδ and Ri:** meet the initial specification in Table 5.	Special preconditioning for 1hr at 150℃ followed by 24hrs. Fix the capacitor to the supporting jig. Expose the capacitors in the condition step 1 through 4 and perform 5 cycles. Step temperature (℃) time **1** θ_A 30 min **2** 25 2~5 min **3** θ_B 30 min **4** 25 2~5 min **NP0(C0G/C0H), X7R:** θ_A =-55℃,θ_B =125℃; **X5R:** θA=-55℃,θB=85℃ **Y5V:** θA=-30℃,θB=85℃ Recover it, let sit at room temperature for 6~24hrs [C0G/C0H(NP0)] or 24±2hrs（X7R、X5R、Y5V）, then observe appearance and measure electrical characteristics.
8	Damp Heat (Steady State)	**Visual:** No visible damage. **Capacitance Change:** **NP0(C0G/C0H)**: ΔC/C ≤ ±5% or ±0.5pF, whichever is larger; **X7R, X5R**: ΔC/C≤±12.5%; **Y5V**: ΔC/C ≤ ±30% **tgδ:** **NP0(C0G/C0H):** tgδ≤20×10^{-4} (C≥30pF) or tgδ≤ $2\times(90/C+7)\times10^{-4}$(C<30pF); **X7R:** tgδ≤$700\times10^{-4}$; **X5R:** tgδ≤$1200\times10^{-4}$ **Y5V:**U_R≥25V tgδ≤950×10^{-4} U_R =16V tgδ≤1300×10^{-4} U_R<16V tgδ≤1600×10^{-4}. **Ri:** **NP0(C0G/C0H):** Ri≥2500MΩ or Ri×C≥50s, which is smaller; **X7R、X5R、Y5V:** Ri≥1000MΩ or Ri×C≥50s (U_R≥25V), which is smaller; Ri≥1000MΩ or Ri×C≥10s (U_R≤16V), which is smaller.	Special preconditioning for 1hr at 150℃ followed by 24hr **Test Temperature:** 60℃ ±2℃ **Humidity:** RH 90~95% **Duration:**500hrs Recover it, let sit at room temperature for 6~24hrs [C0G/C0H(NP0)] or 24±2hrs（X7R、X5R、Y5V）, then observe appearance and measure electrical characteristics.

9	Damp heat with load	**Visual:** No visible damage. **Capacitance Change:** **NP0(C0G/C0H):** ΔC/C≤±7.5% or ±0.75pF, which is larger; **X7R:** ΔC/C≤±12.5%; **X5R:** ΔC/C≤±15%; **Y5V:** ΔC/C≤±30%. **Tgδ:** **NP0(C0G/C0H):** tgδ≤50×10^{-4} (C≥30pF) or tgδ≤ $5\times(90/C+7)\times10^{-4}$(C<30pF); **X7R:** tgδ≤$700\times10^{-4}$; **X5R:** tgδ≤$1200\times10^{-4}$; **Y5V:**$U_R$≥25V tgδ≤$950\times10^{-4}$; U_R =16V tgδ≤1300×10^{-4}; U_R ＜16V tgδ≤1600×10^{-4}. **Ri:** Ri≥500MΩ or Ri×C≥25s, which is smaller	Special preconditioning for 1hr at 150℃. Remove and set for 24hours at room temperature. Perform initial measurement. **Test Temperature:** 60±2℃; **Humidity:** RH 90～95%; **Test Voltage:** 1.0×U_R; **Duration:** 500hrs; Charge/discharge current not exceeds 50mA. Recover it, let sit at room temperature for 6~24hrs [C0G/C0H(NP0)] or 24±2hrs（X7R、X5R、Y5V）, then observe appearance and measure electrical characteristics.（X5R≥100nF Special preconditioning for 1hr at 150 ℃ followed by 24±4hrs）。
10	Endurance	**Visual:** No visible damage. **Capacitance Change:** **NP0(C0G/C0H):** ΔC/C≤±3% or ±0.3pF, which is larger; **X7R, X5R:** ΔC/C≤±15%; **Y5V:** ΔC/C≤±30%. **Tgδ:** **NP0(C0G/C0H)**: tgδ≤20×10^{-4} (C≥30pF) or tgδ≤$2\times(90/C+7)\times10^{-4}$(C<30pF); **X7R**:tgδ≤$700\times10^{-4}$; **X5R**: tgδ≤$1200\times10^{-4}$; **Y5V**:$U_R$≥25V tgδ≤$950\times10^{-4}$ U_R =16V tgδ≤1300×10^{-4} U_R ＜16V tgδ≤1600×10^{-4}. **Ri:** **NP0(C0G/C0H):** Ri≥1000MΩ or Ri×C≥50s,which is smaller; **X7R、X5R、Y5V:** Ri≥1000MΩ or Ri×C≥50s (U_R≥25V), which is smaller; Ri≥1000MΩ or Ri×C≥10s (U_R≤16V), which is smaller.	Special preconditioning for 1hr at 150℃ followed by 24hrs **Test Temperature:** **NP0(C0G/C0H)/X7R:** 125℃; **X5R/ Y5V:** 85℃; **Duration:** 1000hrs; **Test Voltage:** 1.5×U_R Recover it, let sit at room temperature for 6~24hrs [C0G/C0H(NP0)] or 24±2hrs（X7R、X5R、Y5V）, then observe appearance and measure electrical characteristics.（X5R≥100nF Special preconditioning for 1hr at 150 ℃ followed by 24±4hrs）。

4. Packaging, Shipment and storage:

4.1 Packing：

4.1.1Type of packing：

Reel Packaging (standard carrier tape disc packaging), single disc smallest package are shown in Table 4.

4.1.2 Carrier Tape size：

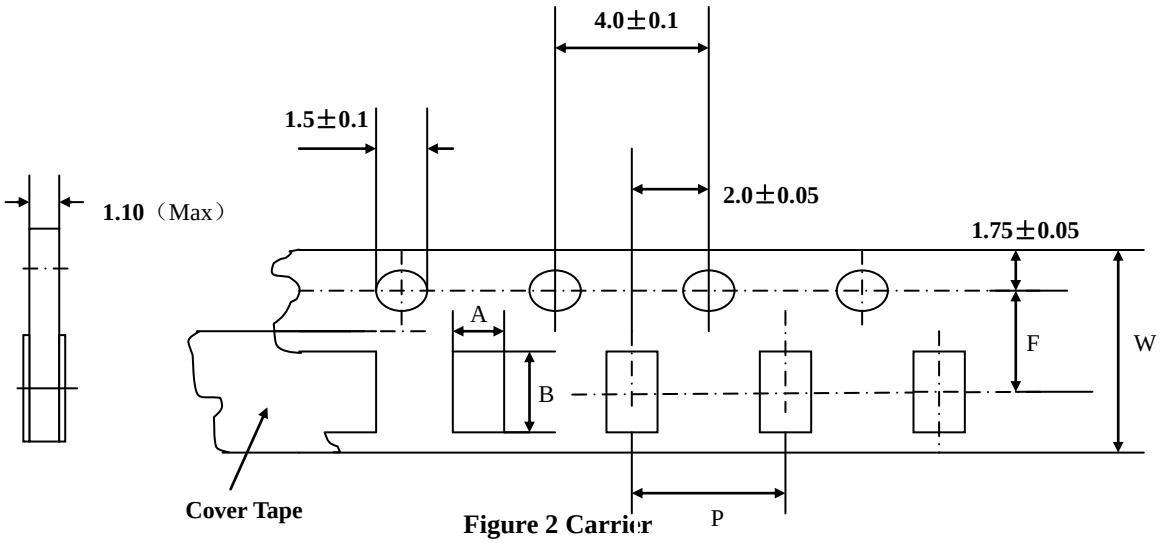


Figure 2 Carrier

Table 7 Carrier size

Mark	Size of product			
	0402	0603	0805	1206
	Size（Unit： mm）			
A （ Width of the square hole ）	0.70±0.10	1.00±0.20	1.60±0.20	2.00±0.20
B （ Length of the square hole ）	1.20±0.10	1.80±0.20	2.40±0.20	3.60±0.20
F （Center distance between positioning hole and square hole ）	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05
P （ Square hole spacing ）	2.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
W （Width of carrier）	8.00±0.20	8.00±0.20	8.00±0.20	8.00±0.20

4.1.3 Disc Size：

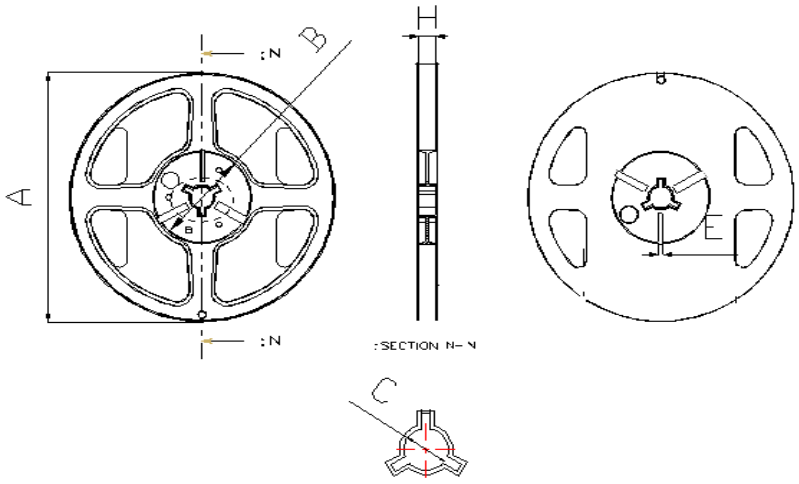
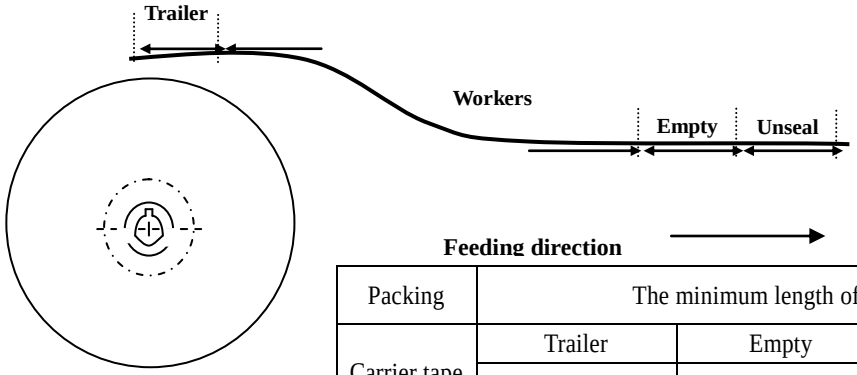


Figure 3 disc

Table 8 Disc Size

Disc Size	A/mm	B/mm	C/mm	E/mm	H/mm
7″	Φ178±2.0	Φ60±2.0	Φ13±1.0	4±1.0	9.5±1.0
13″	Φ330±2.0	Φ100±2.0	Φ13±1.0	3±1.0	10±1.0

4.1.4 Carrier Tape Specifications：



Packing	The minimum length of the reserved spaces		
Carrier tape	Trailer	Empty	Unseal
	60 mm	200mm	160 mm

4.1.5 Performance of Carrier Taping:

4.1.5.1 Strength of Carrier Tape and Top Cover Tape:

a. Carrier Tape

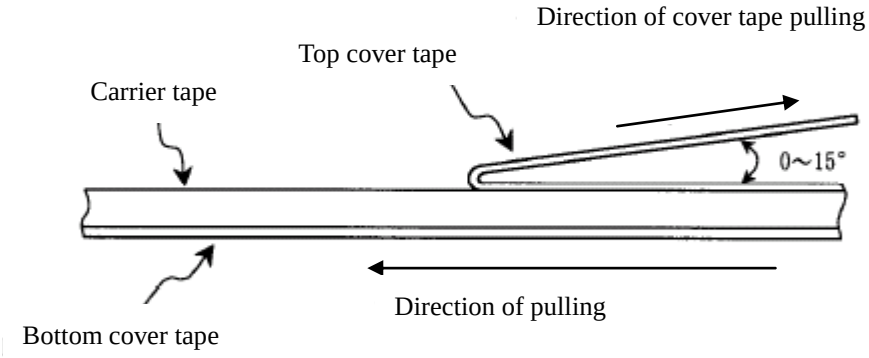
When a tensile force 1.02kgf is applied in the direction to unreel the tape, the tape shall withstand this force.

b. Top cover Tape

When a tensile force 1.02kgf is applied to the tape, the tape shall withstand this force.

4.1.5.2 Peeling Strength of Top Cover Tape:

Unless otherwise specified, the peeling strength of top cover tape shall be within 10.2 to 71.4 gf when the top cover tape is pulled at a speed of 300mm/min with the angle of 0 to 15° (see the following figure).



4.2 Shipment:

It must not be got rain, snow, and must avoid erosion of acid and alkali during the course of shipment.

4.3 Storage:

Period of Store:

12 months, otherwise, its solderability must be inspected again.

Condition of Store:

Temperature: Below 35℃

Humidity: Below RH70％.